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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|--|-------------|----------------------|-------------------------|------------------|
| 10/055,266 | 01/22/2002 | Ki-won Choi | 9898-208 | 6747 |
| 7590 12/12/2003 | | | EXAMINER | |
| MARGER JOHNSON & McCOLLOM, P.C. | | | VU, QUANG D | |
| 1030 S.W. Morrison Street Portland, OR 97205 | | | ART UNIT | PAPER NUMBER |
| | | | 2811 | |
| | | | DATE MAILED: 12/12/2003 | 3 |

Please find below and/or attached an Office communication concerning this application or proceeding.

| A |
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Advisory Action

| Application No. | | Applicant(s) | |
|-----------------|------------|--------------|--|
| | 10/055,266 | CHOI, KI-WON | |
| | Examiner | Art Unit | |
| | Quang D Vu | 2811 | |

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

THE REPLY FILED 13 November 2003 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. Therefore, further action by the applicant is required to avoid abandonment of this application. A proper reply to a final rejection under 37 CFR 1.113 may only be either: (1) a timely filed amendment which places the application in condition for allowance; (2) a timely filed Notice of Appeal (with appeal fee); or (3) a timely filed Request for Continued Examination (RCE) in compliance with 37 CFR 1.114.

| PERIOD FOR REPLY [check either a) or b)] |
|--|
| a) The period for reply expires 3 months from the mailing date of the final rejection. |
| b) The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection. ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f). |
| Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). |
| 1. A Notice of Appeal was filed on Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal. |
| 2. The proposed amendment(s) will not be entered because: |
| (a) They raise new issues that would require further consideration and/or search (see NOTE below); |
| (b) they raise the issue of new matter (see Note below); |
| (c) ☐ they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or |
| (d) they present additional claims without canceling a corresponding number of finally rejected claims. NOTE: |
| 3. Applicant's reply has overcome the following rejection(s): |
| 4. Newly proposed or amended claim(s) would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s). |
| 5. ☐ The a) ☐ affidavit, b) ☐ exhibit, or c) ☐ request for reconsideration has been considered but does NOT place the application in condition for allowance because: <u>See Continuation Sheet.</u> |
| 6. The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection. |
| 7. For purposes of Appeal, the proposed amendment(s) a) will not be entered or b) will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended. |
| The status of the claim(s) is (or will be) as follows: |
| Claim(s) allowed: |
| Claim(s) objected to: |
| Claim(s) rejected: <u>1-10,12-16,26 and 27</u> . |
| Claim(s) withdrawn from consideration: |
| 8. The drawing correction filed on is a) approved or b) disapproved by the Examiner. |
| 9. Note the attached Information Disclosure Statement(s)(PTO-1449) Paper No(s) |
| 10. Other: |
| Steve Loha |

PTOL-303 (Rev. 11-03)

Advisory Action

Part of Paper No 8

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Continuation of 5. does NOT place the application in condition for allowance because: With regards to claims 1, 3-4, 6-10, 13, 16, 26 and 27, the examiner maintains the position that the claimed inventions are anticipated by US Patent No. 6,448,664 to Tay et al. With regards to claims 2, 5, 12, 14 and 15, the examiner maintains the position that the claimed inventions are prima facie obvious over US Patent No 6,448,664 to Tay et al. in view of Admitted Prior Art.

It is argued, in page 7 of the remarks, that Tay et al. do not teach an added wire bonding unit coupled between the redundant bond finger and the added bond finger, wherein the added bond pad is electrically connected to the redundant solder ball pad via the redundant bond finger and the added bond finger. This argument is not persuasive because Tay et al. (figures 9A-B) teach a wire bonding unit (a line connected between bond pad [76] and a pad formed along the first inner rectangle) coupled between the bond pad (76) and a pad formed along the first inner rectangle, wherein the die bond pad (106) is electrically connected to the solder ball (80) via the bond pad (76) and a pad formed along the first inner rectangle. Therefore, a wire bonding unit, die bond pad (106), solder ball (80), bond pad (76) and a pad formed along the first inner rectangle now read on an added wire bonding, the added bond pad, redundant solder ball, redundant bond finger, and the added bond finger, respectively.